

FPGA - Field Programmable Gate Array FPGA - Stratix IV GX 9120 LABs 744 IOs

Manufacturers	Altera Corporation (Intel)
Package/Case	FBGA-1517
Product Type	Programmable Logic ICs
RoHS	Rohs
Lifecycle	



Images are for reference only

Please submit RFQ for EP4SGX230KF40I3N or [Email to us: sales@ovaga.com](mailto:sales@ovaga.com) We will contact you in 12 hours.

[RFQ](#)

General Description

EP4SGX230KF40I3N is a high-end FPGA (Field-Programmable Gate Array) from Intel (formerly Altera), belonging to the Stratix IV GX family.

Features

230,928 Logic Elements (LEs)

16 Embedded Hard IP Protocol Stacks

32 3.125 Gbps low-power transceivers

1,152 M9K memory blocks

24 DSP blocks

1.6 Gbps LVDS performance

1.5V core voltage

40nm process technology

1517 user I/O pins

5.5 Mb on-chip memory

533 MHz maximum operating frequency

Application

Aerospace and Defense: radar systems, satellite communications, image and signal processing, avionics

Communications: high-speed routers and switches, network processors, traffic management systems

Video and Image Processing: video analytics, broadcast equipment, high-resolution video processing, medical imaging

Test and Measurement: automated test equipment, instrumentation, data acquisition



Box Id: 3DGCYAY07

CAUTION


LEVEL

3



This bag contains
MOISTURE SENSITIVE DEVICES



1. Shelf life in sealed bag : 36 months at < 40 C and < 90% relative humidity (RH)
2. After bag is opened, devices that will be subjected to convection reflow, or equivalent processing (peak package body temperature of 245 °C ) must be:
 - a) Mounted within 168 hours at factory conditions of $\leq 30\text{ }^{\circ}\text{C} / 60\%$ RH, or b) Stored at < 10% RH
3. Devices require baking before mounting if :
 - a) Humidity indicator card show humidity > 10% when measured at $23 \pm 5^{\circ}\text{C}$, or b) Condition 2a or 2b is not met.
4. If baking is required, devices may be baked for :
 - a) 12 hours at $125\text{ }^{\circ}\text{C} \pm 5^{\circ}\text{C}$ for high temp. device containers.
 - b) Baking at $40\text{ }^{\circ}\text{C} \pm 5^{\circ}\text{C} / - 0^{\circ}\text{C}$ and < 5% RH for low temperature device containers is **NOT RECOMMENDED**

Bag Seal Date (MM – DD – YY) : 02 – 11 – 13



Note: LEVEL defined by IPC/JEDEC J – STD – 020



2nd Level Interconnect

1. ROHS Compliant – Category e1
2. Maximum safe rework temperature 245 °C

For Rework: mount within 8 hours at factory conditions of
 ≤ 30 °C / 60% RH



ALTERA



Origin: KOREA



PK: P2



Part # EP4SGX230KF40I3N



Lot #: NCFAG40732



FAC#: 1176137501



D/C: H GCFAG1301A



Trace Code: 3R1HA3C0I



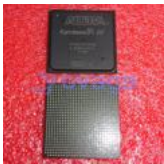
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Box Id: 3DGCYAY07

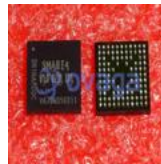
02-11-13 09:40:14

Related Products



[EP4CE55F29C8N](#)

Altera Corporation (Intel)
FBGA-780



[EPM240M100C5N](#)

Altera Corporation (Intel)
BGA-100



[EPM1270T144A5N](#)

Altera Corporation (Intel)
TQFP-144



[EPM570F256C5N](#)

Altera Corporation (Intel)
FBGA-256



[EP2C35F672C8N](#)

Altera Corporation (Intel)
FBGA-672



[EPM7128AETC100-10](#)

Altera Corporation (Intel)
TQFP-100



[EP2C35F484C7N](#)

Altera Corporation (Intel)

FBGA-484



[EP2C35F484I8N](#)

Altera Corporation (Intel)

FBGA-484